



Initial Product/Process Change Notification

Document #: IPCN24762X

Issue Date: 29 Jun 2022

| | |
|--|--|
| Title of Change: | FD3501MNTXG Silicon Revision to Improve Test Time and Yield. |
| Proposed First Ship date: | 05 Nov 2022 or earlier if approved by customer |
| Contact Information: | Contact your local onsemi Sales Office or Peter.Boyle@onsemi.com |
| PCN Samples Contact: | Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements. |
| Type of Notification: | This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com > |
| Marking of Parts/ Traceability of Change: | Top mark silicon revision code will update from A5 to B0 |
| Change Category: | Wafer Fab Change |
| Change Sub-Category(s): | Material Change |
| Sites Affected: | |
| onsemi Sites | External Foundry/Subcon Sites |
| None | TSMC Semiconductor, Taiwan |

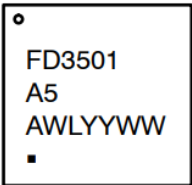
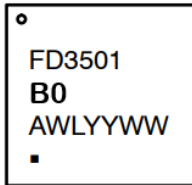
Description and Purpose:

In order to ensure stable production output and capacity onsemi will make an all-layer design revision to improve yield stability and improve production throughput. The following specific changes are made:

- 1) Firmware will be fixed in ROM rather than configured at final test
- 2) SVID buffer IP is updated to improve manufacturability

There is no change to fit, form or function related to this revision and parts may be used interchangeably with no action required by the customer.

Traceability for this change will be handled by a top mark change to indicate the new revision.

| | From | To |
|------------------------|---|---|
| Product marking change |  |  |



Initial Product/Process Change Notification

Document #: IPCN24762X

Issue Date: 29 Jun 2022

Qualification Plan:

QV DEVICE NAME: FD3501MNTXG Rev B0

RMS: 80969

PACKAGE: QFN40 5*5 (485FW)

| Test | Specification | Condition | Interval |
|----------|---------------------------------|---|----------|
| HTOL | JESD22-A108 | Ta=125°C, Vcc = 4.2V | 168 hrs |
| Tri-Temp | N/A | All 48A Parameters, Ta=125°C, Room, -40°C | N/A |
| ESD | 12MSB17722C | HBM, IEC, CDM | |
| LU | JESD78 Class II AEC Q100-004 | -LU, +LU | |

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [**PCN Customized Portal**](#).

| Part Number | Qualification Vehicle |
|-------------|-----------------------|
| FD3501MNTXG | N/A |